| ABBOGIATION CONNECTING<br>ELECTRODICS INDUSTRIES®<br>INDUSTRIES®<br>INDUSTRIES® | ockburn, Illinois. A  | Il rights reserved untions. | under both | This docume<br>level parts, t | ent is a declar<br>he declaration                                   | ation of the an encompass                   | substances<br>es all lowe | within the manufa<br>r level materials fo | cturer listed<br>r which the    | item. No<br>manufac             | ote: if the<br>cturer has | e item is an ass<br>s engineering i | sembly with lower<br>responsibility. |  |  |
|---|---|-----------------------------|------------|-------------------------------|---|---|---------------------------|---|---------------------------------|---------------------------------|---------------------------|-------------------------------------|--------------------------------------|--|--|
|   | IPC Web Site for Information on IPC-1752 Standard Form Type<br>http://www.ipc.org/IPC-175x Distribute |                             |            |                               | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials |   |                           |   |                                 |                                 | s and Mfg Information     |                                     |                                      |  |  |
| Supplier Information  |   |                             |            |                               |   |   |                           |   |                                 |                                 |                           |                                     |                                      |  |  |
| Company name* Company unique ID   |   |                             |            | Unique ID Authority           |   |   |                           |   | Respo                           | Response Date*                  |                           |                                     |                                      |  |  |
| onsemi  | Isemi   |                             |            |                               | 2023-06-08  |   |                           |   |                                 |                                 |                           |                                     |                                      |  |  |
| Contact Name  | Title - Contact   |                             |            |                               | Phone - Contact*  |   |                           |   | Email                           | Email - Contact*                |                           |                                     |                                      |  |  |
| Product-Env-Stewards Product Enviro Compliance                                  |   |                             |            |                               | NA  |   |                           |   | Produ                           | Product-Env-Stewards@onsemi.com |                           |                                     |                                      |  |  |
| uthorized Representative* Title - Representative                                |   |                             |            | ]                             | Phone - Representative*   |   |                           |   | Email                           | Email - Representative*         |                           |                                     |                                      |  |  |
| Product-Env-Stewards  | Enviro Compliance   |                             |            | NA                            |   |   |                           | Produ                                     | Product-Env-Stewards@onsemi.com |                                 |                           |                                     |                                      |  |  |
| Requester Item Number Mfr   | Mfr Item Number Mfr Item Na   |                             | ame        |                               | Effective Da  | te Version                                  | ı I                       | Manufacturing Site                        |                                 | Weight                          | t*                        | UOM                                 | Unit Type                            |  |  |
| FIN   | 11031MTCX 4-ch LVDS Driver  |                             | er         |                               | 2023-06-08 PH4  |   | РН4                       |   | 56.427                          |                                 | mg                        | Each                                |                                      |  |  |
| Manufacturing Proccess Information  |   |                             |            |                               |   |   | I                         |   |                                 |                                 |                           |                                     |                                      |  |  |
| Terminal Plating / Grid Array Material  | Terminal Base   | Ferminal Base Alloy J       |            | L Rating                      | Peak Pr   | k Process Body Temperature Max Time at Peal |                           | eak Temper                                | Temperature Number              |                                 | of Reflow Cyc             | les                                 |                                      |  |  |
| Precious metal (e.g. Ag,Au, NiPdAu) (n<br>Sn)                                   | o CU Alloy  | 1                           |            |                               | <b>260</b> C  |   | С                         | <b>30</b> sec                             |                                 | econds 3                        |                           |                                     |                                      |  |  |
| Comments  |   |                             |            |                               |   |   |                           |   |                                 |                                 |                           |                                     |                                      |  |  |
| evel 1 - maximum time at peak temperature duri                                  | ng soldering is 10-3  | 0 seconds                   |            |                               |   |   |                           |   |                                 |                                 |                           |                                     |                                      |  |  |
| for more information regarding material compos                                  | tion please refer to  | page 3                      |            |                               |   |   |                           |   |                                 |                                 |                           |                                     |                                      |  |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance  | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|--|------------------|--------|---------|-----------------|
| Die                  | 0.74   | mg              | Supplier | Silicon (Si)                                       | 7440-21-3        |        | 0.74    | mg              |
| Die Attach           | 0.084  | mg              | Supplier | Ethylene glycol dicyclopentenyl ether methacrylate | 68586-19-6       |        | 0.0029  | mg              |
|                      |        |                 | Supplier | Bis(a,a-dimethylbenzyl) Peroxide                   | 80-43-3          |        | 0.0005  | mg              |
|                      |        |                 | Supplier | Silver (Ag)  | 7440-22-4        |        | 0.0805  | mg              |
| Lead Frame           | 23.228 | mg              | Supplier | Zinc (Zn)  | 7440-66-6        |        | 0.0279  | mg              |
|                      |        |                 | Supplier | Iron (Fe)  | 7439-89-6        |        | 0.5459  | mg              |
|                      |        |                 | Supplier | Copper (Cu)  | 7440-50-8        |        | 22.6473 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)                                     | 7723-14-0        |        | 0.007   | mg              |
| Mold Compound-Black  | 31.8   | mg              |          | Epoxy resin  | proprietary data |        | 3.021   | mg              |
|                      |        |                 | Supplier | Phenol Resin                                       | Proprietary Data |        | 1.59    | mg              |
|                      |        |                 | Supplier | Carbon Black (C)                                   | 1333-86-4        |        | 0.159   | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)                                | 60676-86-0       |        | 27.03   | mg              |
| Plating              | 0.178  | mg              | Supplier | Palladium (Pd)                                     | 7440-05-3        |        | 0.005   | mg              |
|                      |        |                 | В        | Nickel (Ni)  | 7440-02-0        |        | 0.17    | mg              |
|                      |        |                 | Supplier | Gold (Au)  | 7440-57-5        |        | 0.003   | mg              |
| Wire Bond - Au       | 0.397  | mg              | Supplier | Gold (Au)  | 7440-57-5        |        | 0.397   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).